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	Rigid PCBs (Pool)	Rigid PCBs (Non-Pool)	HDI (1-x-1) without Buried Via	HDI (1-xb-1) with Buried Via	PURE.flex 1F	PURE.flex 2F
Minimum PCB / panel size	30 mm x 15 mm	30 mm x 15 mm	30 mm x 15 mm	30 mm x 15 mm	30 mm x 15 mm (only as a panel)	30 mm x 15 mm (only as a panel)
Minimum PCB / panel size	426 mm x 271 mm	426 mm x 271 mm	426 mm x 271 mm	426 mm x 271 mm	426 mm x 271 mm	426 mm x 271 mm
Material type	TG 150	TG 150	TG 150	TG 150	Polyimide (glueless)	Polyimide (glueless)
Number of layers	1 - 8 layers	1 - 16 layers	4 - 8 layers	4 - 8 layers	1 layer	2 layers
Thickness	0.80 mm 1.00 mm 1.55 mm 2.40 mm	0.50 mm 0.80 mm 1.00 mm 1.55 mm 2.00 mm 2.40 mm 3.20 mm	0.50 mm 0.80 mm 1.00 mm 1.55 mm	0.80 mm 1.00 mm 1.55 mm	0.12 mm	0.17 mm
Structures outside / inside	≥ 192 µm (required for 70 µm) ≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 250 µm (required for 105 µm) ≥ 192 µm (required for 70 µm) ≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC) ≥ 85 µm (required for 18 µm)	≥ 250 µm (required for 105 µm) ≥ 192 µm (required for 70 µm) ≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 250 µm (required for 105 µm) ≥ 192 µm (required for 70 µm) ≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)
Copper outside / inside	35 µm 70 µm	18 µm (no galvanic metalization) 35 µm 70 µm 105 µm	35 µm	35 µm	18 µm 35 µm	18 µm (no galvanic metalization) 35 µm
Finished hole diameter	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)
Smallest routing tool	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm
Laser drills (Micro-Via)	no	no	optional	optional	no	no
Blind via	no	optional	no	no	no	no
Chamfer	no	optional (20° and 45°)	optional (20° and 45°)	optional (20° and 45°)	no	no
Edge plating	no	optional	optional	optional	no	no
Surface finish	ENIG HAL leadfree immersion Tin (Sn)	ENIG HAL leadfree immersion Tin (Sn)	ENIG immersion Tin (Sn)	ENIG immersion Tin (Sn)	ENIG immersion Tin (Sn)	ENIG immersion Tin (Sn)
Hard gold with plating ties	no	optional	optional	optional	no	no
Solder resist	green	green	green	green	green	green
Fully coated silkscreen* ***alternative to colored solder resist**	no	white, yellow, red, blue, black	white, yellow, red, blue, black	white, yellow, red, blue, black	no	no
Partial silkscreen (legend printing)	white	white, yellow, red, blue, black	white, yellow, red, blue, black	white, yellow, red, blue, black	no	no
Plugged Via	no	optional	optional	optional	no	no
E-Test	optional	optional	optional	optional	no	no
UL marking	optional	optional	optional	optional	no	no
Additional documentation	CoC, optional	CoC, optional	CoC, optional	CoC, optional	CoC, optional	CoC, optional

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	RIGID.flex 1F-1Ri	RIGID.flex 1F-3Ri	RIGID.flex 1F-5Ri	PURE.flex with stiffener 1F-Ri	PURE.flex with stiffener 2F-Ri
Minimum PCB / panel size	30 mm x 15 mm (only as a panel)	30 mm x 15 mm (only as a panel)	30 mm x 15 mm (only as a panel)	30 mm x 15 mm (only as a panel)	30 mm x 15 mm (only as a panel)
Minimum PCB / panel size	426 mm x 271 mm (only as a panel)	426 mm x 271 mm (only as a panel)	426 mm x 271 mm (only as a panel)	426 mm x 271 mm	426 mm x 271 mm
Material type	TG 150	TG 150	TG 150	Polyimide (glueless)	Polyimide (glueless)
Number of layers	2 layers	4 layers	6 layers	1 layer	2 layers
Thickness	1.00 mm 1.55 mm	1.00 mm 1.55 mm	1.00 mm 1.55 mm	Stiffener 0.30 mm total	Stiffener 0.30 mm total
Structures outside / inside	≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)	≥ 150 µm ≥ 125 µm ≥ 100 µm (not conform to IPC)
Copper outside / inside	35 µm	outside: 35 µm inside: 18 µm	outside: 35 µm inside: 18 µm	18 µm 35 µm	18 µm (keine galv. Metallisierung) 35 µm
Finished hole diameter	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)	≥ 0.25 mm (Pad ≥ 0.60 mm) ≥ 0.10 mm (Pad ≥ 0.45 mm)
Smallest routing tool	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm	≥ 1.60 mm ≤ 1.50 mm and ≥ 1.10 mm ≤ 1.00 mm and ≥ 0.50 mm
Laser drills (Micro-Via)	no	no	no	no	no
Blind via	no	no	no	no	no
Chamfer	no	no	no	no	no
Edge plating	no	no	no	no	no
Surface finish	ENIG immersion Tin (Sn)	ENIG immersion Tin (Sn)	ENIG immersion Tin (Sn)	ENIG immersion Tin (Sn)	ENIG immersion Tin (Sn)
Hard gold with plating ties	no	no	no	no	no
Solder resist	green	green	green	green	green
Fully coated silkscreen* ***alternative to colored solder resist**	no	no	no	no	no
Partial silkscreen (legend printing)	white, yellow, red, blue, black	white, yellow, red, blue, black	white, yellow, red, blue, black	no	no
Plugged Via	no	no	no	no	no
E-Test	preset	preset	preset	optional	optional
UL marking	optional	optional	optional	no	no
Additional documentation	CoC, optional	CoC, optional	CoC, optional	CoC, optional	CoC, optional